

L Number	Hits	Search Text	DB	Time stamp
1	1	("20010002505").PN.	USPAT; US-PGPUB	2004/01/17 20:58
2	18	(ceramic near chip) and (bak\$3 with (hole\$2 or porous or open\$3 or spac\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:58
3	31	(ceramic near chip) and (burn\$3 with (hole\$2 or porous or open\$3 or spac\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:29
4	24	((ceramic near chip) and (burn\$3 with (hole\$2 or porous or open\$3 or spac\$3)) ) and (@ad<19990330)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:59
5	20	4071880.URPN.	USPAT	2004/01/17 21:20
6	2	("3561110"   "3679950").PN.	USPAT	2004/01/17 21:24
7	20	4071880.URPN.	USPAT	2004/01/17 21:24
8	51	(ceramic near chip) and ((firing or impreganating or additive) with (hole\$2 or porous or open\$3 or spac\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:29
9	40	((ceramic near chip) and ((firing or impreganating or additive) with (hole\$2 or porous or open\$3 or spac\$3)) ) and (@ad<19990330)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:37
10	58323	361/\$.ccls. and (@ad<19990330)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:43
11	279	(361/\$.ccls. and (@ad<19990330) ) and ((ceramic near chip) and (hole\$2 or porous or open\$3 or spac\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:38
12	241	(361/\$.ccls. and (@ad<19990330) ) and ((ceramic near chip) and por\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:39
13	22	((361/\$.ccls. and (@ad<19990330) ) and ((ceramic near chip) and por\$4) ) and ((bak\$3 or firing or burn\$3) with (hole\$2 or porous or open\$3 or spac\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:40
14	30	((361/\$.ccls. and (@ad<19990330) ) and ((ceramic near chip) and por\$4) ) and ((bak\$3 or firing or burn\$3) with (hole\$2 or por\$4 or open\$3 or spac\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:43
15	25	((361/\$.ccls. and (@ad<19990330) ) and ((ceramic near chip) and por\$4) ) and ((bak\$3 or firing or burn\$3) with (hole\$2 or por\$4 or open\$3 or spac\$3)) ) not ((ceramic near chip) and (bak\$3 with (hole\$2 or porous or open\$3 or spac\$3)) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:40

16	310	361/303.ccls. and (@ad<19990330)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:47
17	13	(361/303.ccls. and (@ad<19990330) ) and ((bak\$3 or firing or burn\$3) with (hole\$2 or por\$4 or open\$3 or spac\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:53
18	52	361/308.1.ccls. and (@ad<19990330) and por\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:47
19	5	361/308.1.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:51
20	0	361/314.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:51
21	1	361/315.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:51
22	376	257/\$.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:52
23	90	438/\$.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:52
24	78	(257/\$.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic)) and (438/\$.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:52
25	388	(257/\$.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic)) or (438/\$.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:53
26	27	((257/\$.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic)) or (438/\$.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic))) and ((bak\$3 or firing or burn\$3) with (hole\$2 or por\$4 or open\$3 or spac\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:53
28	165	((257/\$.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic)) or (438/\$.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic))) and ((melt\$3 or heat\$3 or bak\$3 or firing or burn\$3) with (hole\$2 or por\$4 or open\$3 or spac\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 22:22
29	540	(ceramic near chip) and ((hole\$2 or por\$4 or open\$3 or spac\$3 or void) with (electrode\$1 or terminal\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 22:22

30	353	((ceramic near chip) and ((hole\$2 or por\$4 or open\$3 or spac\$3 or void) with (electrode\$1 or terminal\$1)) ) and (@ad<19990330)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 22:23
31	165	((257/\$.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic)) or (438/\$.ccls. and (@ad<19990330) and por\$4 and (chip near ceramic))) and ((melt\$3 or heat\$3 or bak\$3 or firing or burn\$3) with (hole\$2 or por\$4 or open\$3 or spac\$3)) ) and (melt\$3 or heat\$3 or bak\$3 or firing or burn\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 21:59
32	252	((ceramic near chip) and ((hole\$2 or por\$4 or open\$3 or spac\$3 or void) with (electrode\$1 or terminal\$1)) ) and (@ad<19990330)) and (melt\$3 or heat\$3 or bak\$3 or firing or burn\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 22:00
33	42	(ceramic near chip) and ((cellulose or gelatin or carbon) with (electrode\$1 or terminal\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 22:22
34	22	((ceramic near chip) and ((cellulose or gelatin or carbon) with (electrode\$1 or terminal\$1)) ) and (@ad<19990330)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/17 22:23